

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-043497

(43)Date of publication of application : 08.02.2002

(51)Int.Cl. H01L 23/50

(21)Application number : 2000-227077

(71)Applicant : MITSUBISHI ELECTRIC CORP

(22)Date of filing : 27.07.2000

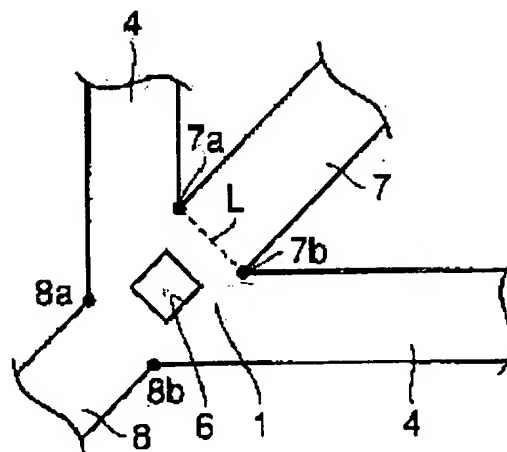
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device having a resin peeling prevention hole and provided with a lead frame difficult to concentrate deformation in the neighborhood thereof.

SOLUTION: The resin peeling prevention hole 5 is provided on the intersection part 1 of a reinforcing frame 4 and an inside hanging lead 7 in the lead frame, and positioned on the intersection part of the area of the contrary side of a die pad rather than a line L connecting first and second inside hanging lead root boundary points 7a, 7b being a point in which the reinforcing frame continues to both the side parts of an inside hanging lead extending from the intersection part.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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